

Seung-Boo Jung

List of Publications by Year in descending order

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363
papers

7,520
citations

70961

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all docs

364
docs citations

364
times ranked

3909
citing authors

#	ARTICLE	IF	CITATIONS
1	Effects of intermetallic compound on the electrical and mechanical properties of friction welded Cu/Al bimetallic joints during annealing. <i>Journal of Alloys and Compounds</i> , 2005, 390, 212-219.	2.8	301
2	The joint properties of copper by friction stir welding. <i>Materials Letters</i> , 2004, 58, 1041-1046.	1.3	236
3	Microstructural investigation of friction stir welded pure titanium. <i>Materials Letters</i> , 2005, 59, 3315-3318.	1.3	181
4	Wettability and interfacial reactions of Sn-Ag-Cu/Cu and Sn-Ag-Ni/Cu solder joints. <i>Journal of Alloys and Compounds</i> , 2009, 486, 142-147.	2.8	118
5	IMC morphology, interfacial reaction and joint reliability of Pb-free Sn-Ag-Cu solder on electrolytic Ni BGA substrate. <i>Journal of Alloys and Compounds</i> , 2005, 392, 247-252.	2.8	112
6	Interfacial reactions and growth kinetics for intermetallic compound layer between In-48Sn solder and bare Cu substrate. <i>Journal of Alloys and Compounds</i> , 2005, 386, 151-156.	2.8	109
7	Formation of intermetallic compounds in Al and Mg alloy interface during friction stir spot welding. <i>Intermetallics</i> , 2011, 19, 125-130.	1.8	109
8	Interfacial reaction and mechanical properties of eutectic Sn-0.7Cu/Ni BGA solder joints during isothermal long-term aging. <i>Journal of Alloys and Compounds</i> , 2005, 391, 82-89.	2.8	105
9	Intermetallic compound layer growth at the interface between Sn-Cu-Ni solder and Cu substrate. <i>Journal of Alloys and Compounds</i> , 2004, 381, 151-157.	2.8	99
10	Microstructures and wear property of friction stir welded AZ91 Mg/SiC particle reinforced composite. <i>Composites Science and Technology</i> , 2006, 66, 1513-1520.	3.8	89
11	Effect of Isothermal Aging on Ball Shear Strength in BGA Joints with Sn-3.5Ag-0.75Cu Solder. <i>Materials Transactions</i> , 2002, 43, 1858-1863.	0.4	86
12	Growth of an intermetallic compound layer with Sn-3.5Ag-5Bi on Cu and Ni-P/Cu during aging treatment. <i>Journal of Electronic Materials</i> , 2003, 32, 1195-1202.	1.0	83
13	Effects of copper insert layer on the properties of friction welded joints between TiAl and AISI 4140 structural steel. <i>Intermetallics</i> , 2004, 12, 671-678.	1.8	83
14	Comparative Study of ENIG and ENEPIG as Surface Finishes for a Sn-Ag-Cu Solder Joint. <i>Journal of Electronic Materials</i> , 2011, 40, 1950-1955.	1.0	82
15	Investigation of interfacial reactions between Sn-5Bi solder and Cu substrate. <i>Journal of Alloys and Compounds</i> , 2003, 359, 202-208.	2.8	79
16	Interfacial reactions between Sn-0.4Cu solder and Cu substrate with or without ENIG plating layer during reflow reaction. <i>Journal of Alloys and Compounds</i> , 2005, 396, 122-127.	2.8	79
17	The Joint Characteristics of Friction Stir Welded AZ91D Magnesium Alloy. <i>Materials Transactions</i> , 2003, 44, 917-923.	0.4	78
18	Interfacial reactions and shear strengths between Sn-Ag-based Pb-free solder balls and Au/EN/Cu metallization. <i>Journal of Electronic Materials</i> , 2004, 33, 1182-1189.	1.0	78

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19	Experimental and finite element analysis of the shear speed effects on the Sn-Ag and Sn-Ag-Cu BGA solder joints. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2004, 371, 267-276.	2.6	75
20	Reliability investigation and interfacial reaction of ball-grid-array packages using the lead-free Sn-Cu solder. <i>Journal of Electronic Materials</i> , 2004, 33, 1190-1199.	1.0	74
21	Lap joint properties of FSWed dissimilar formed 5052 Al and 6061 Al alloys with different thickness. <i>Journal of Materials Science</i> , 2008, 43, 3296-3304.	1.7	73
22	Sequential interfacial intermetallic compound formation of Cu ₆ Sn ₅ and Ni ₃ Sn ₄ between Sn-Ag-Cu solder and ENEPIG substrate during a reflow process. <i>Journal of Alloys and Compounds</i> , 2011, 509, L153-L156.	2.8	70
23	Effects of Cr ₃ C ₂ on the microstructure and mechanical properties of the brazed joints between WC-Co and carbon steel. <i>International Journal of Refractory Metals and Hard Materials</i> , 2006, 24, 215-221.	1.7	65
24	Characteristic evaluation of electroless nickel-phosphorus deposits with different phosphorus contents. <i>Microelectronic Engineering</i> , 2007, 84, 2552-2557.	1.1	62
25	Growth kinetics of Ni ₃ Sn ₄ and Ni ₃ P layer between Sn-3.5Ag solder and electroless Ni-P substrate. <i>Journal of Alloys and Compounds</i> , 2004, 376, 105-110.	2.8	61
26	Effect of surface finish material on printed circuit board for electrochemical migration. <i>Microelectronics Reliability</i> , 2008, 48, 652-656.	0.9	61
27	The Effect of Bi Concentration on Wettability of Cu Substrate by Sn-Bi Solders. <i>Materials Transactions</i> , 2001, 42, 751-755.	0.4	60
28	Effect of reflow time on interfacial reaction and shear strength of Sn-0.7Cu solder/Cu and electroless Ni-P BGA joints. <i>Journal of Alloys and Compounds</i> , 2004, 385, 192-198.	2.8	60
29	Behavior of β^2 phase (Al ₃ Mg ₂) in AA 5083 during friction stir welding. <i>Intermetallics</i> , 2013, 35, 120-127.	1.8	59
30	Effect of isothermal aging on intermetallic compound layer growth at the interface between Sn-3.5Ag-0.75Cu solder and Cu substrate. <i>Journal of Materials Science</i> , 2004, 39, 4211-4217.	1.7	58
31	Interfacial reactions and shear strength on Cu and electrolytic Au/Ni metallization with Sn-Zn solder. <i>Journal of Materials Research</i> , 2006, 21, 1590-1599.	1.2	58
32	Hydrothermally Grown In-doped ZnO Nanorods on p-GaN Films for Color-tunable Heterojunction Light-emitting-diodes. <i>Scientific Reports</i> , 2015, 5, 10410.	1.6	58
33	Cu-Sn and Ni-Sn transient liquid phase bonding for die-attach technology applications in high-temperature power electronics packaging. <i>Journal of Materials Science: Materials in Electronics</i> , 2017, 28, 7827-7833.	1.1	57
34	Direct Metallization of Gold Nanoparticles on a Polystyrene Bead Surface using Cationic Gold Ligands. <i>Macromolecular Rapid Communications</i> , 2007, 28, 634-640.	2.0	56
35	Design and fabrication of screen-printed silver circuits for stretchable electronics. <i>Microelectronic Engineering</i> , 2014, 120, 216-220.	1.1	52
36	Synergistic effect of Indium and Gallium co-doping on growth behavior and physical properties of hydrothermally grown ZnO nanorods. <i>Scientific Reports</i> , 2017, 7, 41992.	1.6	50

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37	Effect of aging conditions on interfacial reaction and mechanical joint strength between Sn-3.0Ag-0.5Cu solder and Ni-P UBM. <i>Materials Science and Engineering B: Solid-State Materials for Advanced Technology</i> , 2005, 121, 204-210.	1.7	47
38	Mechanical property of the epoxy-contained Sn-58Bi solder with OSP surface finish. <i>Journal of Alloys and Compounds</i> , 2014, 615, S411-S417.	2.8	47
39	Evaluation of Electrochemical Migration on Flexible Printed Circuit Boards with Different Surface Finishes. <i>Journal of Electronic Materials</i> , 2009, 38, 902-907.	1.0	45
40	Enhanced Electrical and Mechanical Properties of Silver Nanoplatelet-Based Conductive Features Direct Printed on a Flexible Substrate. <i>ACS Applied Materials & Interfaces</i> , 2013, 5, 5908-5913.	4.0	45
41	Effect of substrate metallization on mechanical properties of Sn-3.5Ag BGA solder joints with multiple reflows. <i>Microelectronic Engineering</i> , 2005, 82, 569-574.	1.1	43
42	Effect of Pin Shapes on Joint Characteristics of Friction Stir Spot Welded AA5J32 Sheet. <i>Materials Transactions</i> , 2010, 51, 1028-1032.	0.4	43
43	Fabrication of SiCp/AA5083 composite via friction stir welding. <i>Transactions of Nonferrous Metals Society of China</i> , 2012, 22, s634-s638.	1.7	42
44	Interfacial reaction and intermetallic compound formation of Sn-1Ag/ENIG and Sn-1Ag/ENEPIG solder joints. <i>Journal of Alloys and Compounds</i> , 2015, 627, 276-280.	2.8	42
45	Title is missing!. <i>Journal of Materials Science: Materials in Electronics</i> , 2003, 14, 487-493.	1.1	41
46	Reliability evaluation of Au-20Sn flip chip solder bump fabricated by sequential electroplating method with Sn and Au. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2008, 473, 119-125.	2.6	41
47	Cu-Sn Intermetallic Compound Joints for High-Temperature Power Electronics Applications. <i>Journal of Electronic Materials</i> , 2018, 47, 430-435.	1.0	41
48	Effect of immersion Ag surface finish on interfacial reaction and mechanical reliability of Sn-3.5Ag-0.7Cu solder joint. <i>Journal of Alloys and Compounds</i> , 2008, 458, 200-207.	2.8	40
49	Effects of cerium content on wettability, microstructure and mechanical properties of Sn-Ag-Ce solder alloys. <i>Journal of Alloys and Compounds</i> , 2010, 499, 154-159.	2.8	40
50	Effect of surface finish on interfacial reactions of Cu/Sn-Ag-Cu/Cu(ENIG) sandwich solder joints. <i>Journal of Alloys and Compounds</i> , 2008, 448, 177-184.	2.8	39
51	Interfacial reactions and mechanical strength of Sn-3.0Ag-0.5Cu/Ni/Cu and Au-20Sn/Ni/Cu solder joints for power electronics applications. <i>Microelectronics Reliability</i> , 2017, 71, 119-125.	0.9	37
52	Effect of Surface Finishes on Ball Shear Strength in BGA Joints with Sn-3.5 mass%Ag Solder. <i>Materials Transactions</i> , 2002, 43, 751-756.	0.4	36
53	Reliability studies of Sn-9Zn/Cu solder joints with aging treatment. <i>Journal of Alloys and Compounds</i> , 2006, 407, 141-149.	2.8	36
54	Effects of third element and surface finish on interfacial reactions of Sn-Ag-xCu (or Ni)/(Cu or ENIG) solder joints. <i>Journal of Alloys and Compounds</i> , 2010, 506, 331-337.	2.8	36

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55	Microstructure and mechanical property of A356 based composite by friction stir processing. Transactions of Nonferrous Metals Society of China, 2013, 23, 335-340.	1.7	36
56	Void Free Friction Stir Weld Zone Of The Dissimilar 6061 Aluminum And Copper Joint By Shifting The Tool Insertion Location. Materials Research Innovations, 2004, 8, 93-96.	1.0	35
57	Characteristics of environmental factor for electrochemical migration on printed circuit board. Journal of Materials Science: Materials in Electronics, 2008, 19, 952-956.	1.1	35
58	Microstructure and Mechanical Properties of Friction Stir Spot Welded Galvanized Steel. Materials Transactions, 2010, 51, 1044-1050.	0.4	35
59	Effect of SiC particles on microstructure and mechanical property of friction stir processed AA6061-T4. Transactions of Nonferrous Metals Society of China, 2012, 22, s614-s618.	1.7	35
60	Interfacial reaction of ENIG/Sn-Ag-Cu/ENIG sandwich solder joint during isothermal aging. Microelectronic Engineering, 2006, 83, 2329-2334.	1.1	34
61	Effect of displacement rate on ball shear properties for Sn ³⁷ Pb and Sn ^{3.5} Ag BGA solder joints during isothermal aging. Microelectronics Reliability, 2007, 47, 2169-2178.	0.9	34
62	Die-attach for power devices using the Ag sintering process: Interfacial microstructure and mechanical strength. Metals and Materials International, 2017, 23, 958-963.	1.8	34
63	Effect of Microstructure on Mechanical Properties of Friction-Welded Joints between Ti and AISI 321 Stainless Steel. Materials Transactions, 2004, 45, 2805-2811.	0.4	33
64	Interfacial reactions and joint reliability of Sn ⁹ Zn solder on Cu or electrolytic Au/Ni/Cu BGA substrate. Microelectronic Engineering, 2005, 82, 561-568.	1.1	33
65	Evaluation of solder joint reliability in flip-chip packages during accelerated testing. Journal of Electronic Materials, 2005, 34, 1550-1557.	1.0	33
66	Solid-state interfacial reactions between Sn ^{3.5} Ag ^{0.7} Cu solder and electroless Ni-immersion Au substrate during high temperature storage test. Journal of Alloys and Compounds, 2007, 439, 91-96.	2.8	33
67	Effects of isothermal aging and temperature-humidity treatment of substrate on joint reliability of Sn ^{3.0} Ag ^{0.5} Cu/OSP-finished Cu CSP solder joint. Microelectronics Reliability, 2008, 48, 1864-1874.	0.9	33
68	Hybrid Friction Stir Welding of High-carbon Steel. Journal of Materials Science and Technology, 2011, 27, 127-130.	5.6	33
69	Liquid-state and solid-state interfacial reactions of fluxless-bonded Au ²⁰ Sn/ENIG solder joint. Journal of Alloys and Compounds, 2009, 469, 108-115.	2.8	32
70	Effect of multiple reflows on interfacial reaction and shear strength of Sn ⁴ Ag electroplated solder bumps for flip chip package. Microelectronic Engineering, 2010, 87, 517-521.	1.1	32
71	Photo-induced fabrication of Ag nanowire circuitry for invisible, ultrathin, conformable pressure sensors. Journal of Materials Chemistry C, 2017, 5, 9986-9994.	2.7	32
72	Solid state interfacial reaction and joint strength of Sn ³⁷ Pb solder with Ni ⁴ P under bump metallization in flip chip application. Journal of Alloys and Compounds, 2005, 395, 80-87.	2.8	31

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73	Evaluation of displacement rate effect in shear test of Sn-3Ag-0.5Cu solder bump for flip chip application. <i>Microelectronics Reliability</i> , 2006, 46, 535-542.	0.9	31
74	Investigation of interfacial reaction between Au-Sn solder and Kovar for hermetic sealing application. <i>Microelectronic Engineering</i> , 2007, 84, 2634-2639.	1.1	31
75	Au-Sn flip-chip solder bump for microelectronic and optoelectronic applications. <i>Microsystem Technologies</i> , 2007, 13, 1463-1469.	1.2	31
76	Effect of surface finishes on electromigration reliability in eutectic Sn-58Bi solder joints. <i>Microelectronic Engineering</i> , 2014, 120, 77-84.	1.1	31
77	Characterization of the shear test method with low melting point In-48Sn solder joints. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2005, 397, 145-152.	2.6	30
78	Interfacial reactions and joint strength of Sn-37Pb and Sn-3.5Ag solders with immersion Ag-plated Cu substrate during aging at 150 °C. <i>Journal of Materials Research</i> , 2006, 21, 3196-3204.	1.2	30
79	Reliability analysis of Au-Sn flip-chip solder bump fabricated by co-electroplating. <i>Journal of Materials Research</i> , 2007, 22, 1219-1229.	1.2	30
80	Effect of Sintering Conditions on the Mechanical Strength of Cu-Sintered Joints for High-Power Applications. <i>Materials</i> , 2018, 11, 2105.	1.3	30
81	Effects of reflow and cooling conditions on interfacial reaction and IMC morphology of Sn-Cu/Ni solder joint. <i>Journal of Alloys and Compounds</i> , 2006, 415, 56-61.	2.8	29
82	Failure mechanism of Pb-bearing and Pb-free solder joints under high-speed shear loading. <i>Metals and Materials International</i> , 2010, 16, 7-12.	1.8	29
83	Microstructure, Electrical Properties, and Electrochemical Migration of a Directly Printed Ag Pattern. <i>Journal of Electronic Materials</i> , 2011, 40, 35-41.	1.0	29
84	Electrically and mechanically enhanced Ag nanowires-colorless polyimide composite electrode for flexible capacitive sensor. <i>Applied Surface Science</i> , 2016, 380, 223-228.	3.1	29
85	Mechanical reliability of Sn-rich Au-Sn/Ni flip chip solder joints fabricated by sequential electroplating method. <i>Microelectronics Reliability</i> , 2008, 48, 1857-1863.	0.9	28
86	Electrochemical migration behavior of silver nanopaste screen-printed for flexible and printable electronics. <i>Current Applied Physics</i> , 2013, 13, S190-S194.	1.1	28
87	Mechanical properties of Sn-58wt%Bi solder containing Ag-decorated MWCNT with thermal aging tests. <i>Journal of Alloys and Compounds</i> , 2020, 820, 153077.	2.8	28
88	Reexamination of the solder ball shear test for evaluation of the mechanical joint strength. <i>International Journal of Solids and Structures</i> , 2006, 43, 1928-1945.	1.3	27
89	Reliability of adhesive interconnections for application in display module. <i>Microelectronic Engineering</i> , 2007, 84, 2691-2696.	1.1	27
90	Effect of reflow numbers on the interfacial reaction and shear strength of flip chip solder joints. <i>Journal of Alloys and Compounds</i> , 2008, 458, 253-260.	2.8	27

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91	Characterization of direct patterned Ag circuits for RF application. <i>Microelectronic Engineering</i> , 2010, 87, 379-382.	1.1	27
92	Effect of laminating parameters on the adhesion property of flexible copper clad laminate with adhesive layer. <i>International Journal of Adhesion and Adhesives</i> , 2010, 30, 30-35.	1.4	27
93	Drop Reliability of Epoxy-contained Sn-58wt.%Bi Solder Joint with ENIG and ENEPIG Surface Finish Under Temperature and Humidity Test. <i>Journal of Electronic Materials</i> , 2016, 45, 3651-3658.	1.0	27
94	Effects of silver additions on the mechanical properties and resistance to thermal shock of YBa ₂ Cu ₃ O _{7-x} superconductors. <i>Cryogenics</i> , 1999, 39, 107-113.	0.9	26
95	Effects of Ag content on the reliability of LED package component with Sn-Bi-Ag solder. <i>Journal of Materials Science: Materials in Electronics</i> , 2015, 26, 8707-8713.	1.1	26
96	Effects of bonding pressure on the thermo-mechanical reliability of ACF interconnection. <i>Microelectronic Engineering</i> , 2006, 83, 2335-2340.	1.1	25
97	Mechanical reliability evaluation of Sn-37Pb solder joint using high speed lap-shear test. <i>Microelectronic Engineering</i> , 2008, 85, 1967-1970.	1.1	25
98	Effect of high-speed loading conditions on the fracture mode of the BGA solder joint. <i>Microelectronics Reliability</i> , 2008, 48, 1882-1889.	0.9	25
99	The characteristics of Cu nanopaste sintered by atmospheric-pressure plasma. <i>Microelectronic Engineering</i> , 2013, 107, 121-124.	1.1	25
100	A UV-responsive pressure sensitive adhesive for damage-free fabrication of an ultrathin imperceptible mechanical sensor with ultrahigh optical transparency. <i>Journal of Materials Chemistry A</i> , 2019, 7, 22588-22595.	5.2	25
101	Mechanical, electrical, and thermal reliability of Sn-58wt.%Bi solder joints with Ag-decorated MWCNT for LED package component during aging treatment. <i>Composites Part B: Engineering</i> , 2020, 182, 107617.	5.9	25
102	Mechanical properties of copper to titanium joined by friction welding. <i>Journal of Materials Science</i> , 2003, 38, 1281-1287.	1.7	24
103	Effect of boron content in electroless Ni-B layer on plating layer properties and soldering characteristics with Sn-Ag solder. <i>Journal of Alloys and Compounds</i> , 2008, 466, 73-79.	2.8	24
104	Analysis of Failure Mechanism in Anisotropic Conductive and Non-Conductive Film Interconnections. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2008, 31, 65-73.	1.4	24
105	Effect of Pd Addition in ENIG Surface Finish on Drop Reliability of Sn-Ag-Cu Solder Joint. <i>Materials Transactions</i> , 2011, 52, 1553-1559.	0.4	24
106	Electrical properties and electrochemical migration characteristics of directly printed Ag patterns with various sintering conditions. <i>Microelectronics Reliability</i> , 2014, 54, 410-416.	0.9	24
107	Electromigration behaviors of Sn58%Bi solder containing Ag-coated MWCNTs with OSP surface finished PCB. <i>Journal of Alloys and Compounds</i> , 2019, 775, 581-588.	2.8	24
108	Comparison of Interfacial Stability of Pb-Free Solders (Sn-3.5Ag, Sn-3.5Ag-0.7Cu, and Sn-0.7Cu) on ENIG-Plated Cu During Aging. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2010, 33, 64-70.	1.4	23

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109	Interfacial reaction between Au-Sn solder and Au/Ni-metallized Kovar. Journal of Materials Science: Materials in Electronics, 2011, 22, 84-90.	1.1	23
110	Fabrication and adhesion strength of Cu/Ni-Cr/polyimide films for flexible printed circuits. Microelectronic Engineering, 2011, 88, 1024-1027.	1.1	23
111	Effect of epoxy content in Ag nanoparticle paste on the bonding strength of MLCC packages. Applied Surface Science, 2019, 495, 143487.	3.1	23
112	Bonding of power device to ceramic substrate using Sn-coated Cu micro paste for high-temperature applications. Applied Surface Science, 2020, 515, 146060.	3.1	23
113	Reliability of In-48Sn solder/Au/Ni/Cu BGA packages during reflow process. Journal of Electronic Materials, 2005, 34, 1565-1572.	1.0	22
114	Characterization of Interfacial Reaction Layers Formed Between Sn-3.5Ag Solder and Electroless Ni-Immersion Au-Plated Cu Substrates. Journal of Electronic Materials, 2008, 37, 84-89.	1.0	22
115	Failure behaviors of BGA solder joints under various loading conditions of high-speed shear test. Journal of Materials Science: Materials in Electronics, 2009, 20, 17-24.	1.1	22
116	Adhesion characteristics of Cu/Ni-Cr/polyimide flexible copper clad laminates according to Ni:Cr ratio and Cu electroplating layer thickness. Journal of Materials Science: Materials in Electronics, 2009, 20, 885-890.	1.1	22
117	Electrochemical migration of directly printed Ag electrodes using Ag paste with epoxy binder. Microelectronic Engineering, 2013, 103, 1-6.	1.1	22
118	Friction welding of TiAl and AISI4140. Journal of Materials Science, 2004, 39, 1125-1128.	1.7	21
119	High temperature reliability and interfacial reaction of eutectic Sn-0.7Cu/Ni solder joints during isothermal aging. Microelectronics Reliability, 2006, 46, 905-914.	0.9	21
120	Evaluation of solder joint reliability in flip chip package under thermal shock test. Thin Solid Films, 2006, 504, 426-430.	0.8	21
121	Fabrication of the hybrid Ag paste combined by Ag nanoparticle and micro Ag flake and its flexibility. Journal of Alloys and Compounds, 2017, 699, 1186-1191.	2.8	21
122	Effect of Ni(P) thickness in Au/Pd/Ni(P) surface finish on the electrical reliability of Sn-3.0Ag-0.5Cu solder joints during current-stressing. Journal of Alloys and Compounds, 2021, 850, 156729.	2.8	21
123	Interfacial reactions and intermetallic compound growth between indium and copper. Journal of Materials Science: Materials in Electronics, 2004, 15, 95-98.	1.1	20
124	Effect of isothermal aging on the interfacial reactions between Sn-0.4Cu solder and Cu substrate with or without ENIG plating layer. Surface and Coatings Technology, 2006, 200, 4440-4447.	2.2	20
125	Mechanical Property Evaluation of Sn-3.0Ag-0.5Cu BGA Solder Joints Using High-Speed Ball Shear Test. Journal of Electronic Materials, 2009, 38, 2489-2495.	1.0	20
126	Structure&Properties Relations in Friction Stir Spot Welded Low Carbon Steel Sheets for Light Weight Automobile Body. Materials Transactions, 2010, 51, 399-403.	0.4	20

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127	Intense pulsed light surface treatment for improving adhesive bonding of aluminum and carbon fiber reinforced plastic (CFRP). <i>Composite Structures</i> , 2021, 258, 113364.	3.1	20
128	Effect of thermal treatment on adhesion strength of Cu/Ni/Cr/polyimide flexible copper clad laminate fabricated by roll-to-roll process. <i>Microelectronic Engineering</i> , 2011, 88, 718-723.	1.1	19
129	Enhancing Adhesion of Screen-Printed Silver Nanopaste Films. <i>Advanced Materials Interfaces</i> , 2015, 2, 1500283.	1.9	19
130	Effects of Precursor Concentration on Morphology of MoS ₂ Nanosheets by Hydrothermal Synthesis. <i>Journal of Nanoscience and Nanotechnology</i> , 2016, 16, 11548-11551.	0.9	19
131	Effect of surface finish metallization on mechanical strength of Ag sintered joint. <i>Microelectronic Engineering</i> , 2018, 198, 15-21.	1.1	19
132	Pressureless die attach by transient liquid phase sintering of Cu nanoparticles and Sn-58Bi particles assisted by polyvinylpyrrolidone dispersant. <i>Journal of Alloys and Compounds</i> , 2019, 781, 657-663.	2.8	19
133	Investigations of the test parameters and bump structures in the shear test of flip chip solder bump. <i>Thin Solid Films</i> , 2006, 504, 405-409.	0.8	18
134	Electromigration Behavior in Sn-37Pb and Sn-3.0Ag-0.5Cu Flip-Chip Solder Joints under High Current Density. <i>Journal of Electronic Materials</i> , 2009, 38, 70-77.	1.0	18
135	Evaluation of the Bondability of the Epoxy-Enhanced Sn-58Bi Solder with ENIG and ENEPIG Surface Finishes. <i>Journal of Electronic Materials</i> , 2015, 44, 4637-4645.	1.0	18
136	Effects of Aging Treatment on Mechanical Properties of Sn-58Bi Epoxy Solder on ENEPIG-Surface-Finished PCB. <i>Journal of Electronic Materials</i> , 2016, 45, 5895-5903.	1.0	18
137	Effects of crystalline and amorphous Pd layers on initial interfacial reactions at Sn-3.0Ag-0.5Cu/thin-Au/Pd/Ni(P) solder joints. <i>Applied Surface Science</i> , 2020, 503, 144339.	3.1	18
138	Effect of surface finish of substrate on mechanical reliability of In-48Sn solder joints in MOEMS package. <i>Microsystem Technologies</i> , 2007, 13, 1567-1573.	1.2	17
139	Reliability of Conductive Adhesives as a Pb-free Alternative in Flip-Chip Applications. <i>Journal of Electronic Materials</i> , 2008, 37, 9-16.	1.0	17
140	Mechanical and Electrical Properties of Cu/Sn-3.5Ag/Cu Ball Grid Array (BGA) Solder Joints after Multiple Reflows. <i>Journal of Electronic Materials</i> , 2008, 37, 118-124.	1.0	17
141	Flexibility of Silver Conductive Circuits Screen-Printed on a Polyimide Substrate. <i>Journal of Nanoscience and Nanotechnology</i> , 2011, 11, 1493-1498.	0.9	17
142	Effects of sintering conditions on microstructure and characteristics of screen-printed Ag thin film. <i>Electronic Materials Letters</i> , 2012, 8, 309-314.	1.0	17
143	Fabrication of Ag-MWNT nanocomposite paste for high-power LED package. <i>Current Applied Physics</i> , 2015, 15, S36-S41.	1.1	17
144	Comparative study of ENEPIG and thin ENEPIG as surface finishes for SAC305 solder joints. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 4724-4731.	1.1	17

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145	Microstructural evolution and interfacial reactions of fluxless-bonded Au-20Sn/Cu solder joint during reflow and aging. <i>Journal of Materials Research</i> , 2007, 22, 2817-2824.	1.2	16
146	Investigation of interfacial reaction and joint reliability between eutectic Sn-3.5Ag solder and ENIG-plated Cu substrate during high temperature storage test. <i>Journal of Materials Science: Materials in Electronics</i> , 2007, 18, 559-567.	1.1	16
147	Fabrication of two-layer flexible copper clad laminate by electroless-Cu plating on surface modified polyimide. <i>Transactions of Nonferrous Metals Society of China</i> , 2009, 19, 970-974.	1.7	16
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